

ABSTRACT

A method of manufacturing a semiconductor device includes (a) connecting a first substrate with a second substrate disposed to be stacked on the first substrate and (b) cutting the first substrate and the second substrate in the same process with a cutting tool. The cutting tool includes a plurality of cutters disposed close to each other, having different cut widths and the first substrate and the second substrate are cut with the cutting tool so that the first substrate and the second substrate have different cut widths, in step (b).